





Assembly

LEAD OR BUMP ATTACH

Leadframe Insertion:

-  Die-Tech 3002-1 SIP Inserters (2)
-  Die-Tech 3002-2 SIP Inserter (1)
-  Die-Tech 4004-1 DIP Leadframe Inserter (1)

Leadframe Soldering:

-  Comatel Comwave Nitrogen 9180 In-Line Soldering System (1)
-  Gelzer Rotary SIP Leadframe Soldering System (1)

Pin Insertion:

-  AutoSplice Pin Insertion Machine (1)

Solder Bumping:

-  Stencil Print Bumping Process
-  Stencil Transfer Ball Placement System